MPI TS3000-DS | 300 mm Automated Probe System

Single- & Doubled Sided EIC-PIC (EPIC) Wafer Probe System, Supporting CPO and COUPE* Device Characterization

Microscope and Optics Options

- Stable microscope bridge mount with 50 x 50 x 140 mm programmable movement
- Various optics options available such as MPI AMZ12 with up to 12x optical zoom or MPI iMAG® - the digital microscope
- Probe-To-Pad-Alignment (PTPA) for vertical probe cards

Optical Setup

- Hexapod+NanoPositioner combination
- Vertical, horizontal and trench coupling
- East, West, or East+West configurations
- Top or bottom configuration

Electrical Setup

- Probe card in 4.5 inch width format
- DC and RF MicroPositioners
- Top side configuration
- Optional high-pin count support, up to 35 kg force

MicroPositioners

- Supports up to 4 RF and 10 DC MicroPositioner
- Wide range of MicroPositioners available
- Dedicated Coax, Triax and Kelvin probe arms

Top Probe Platen

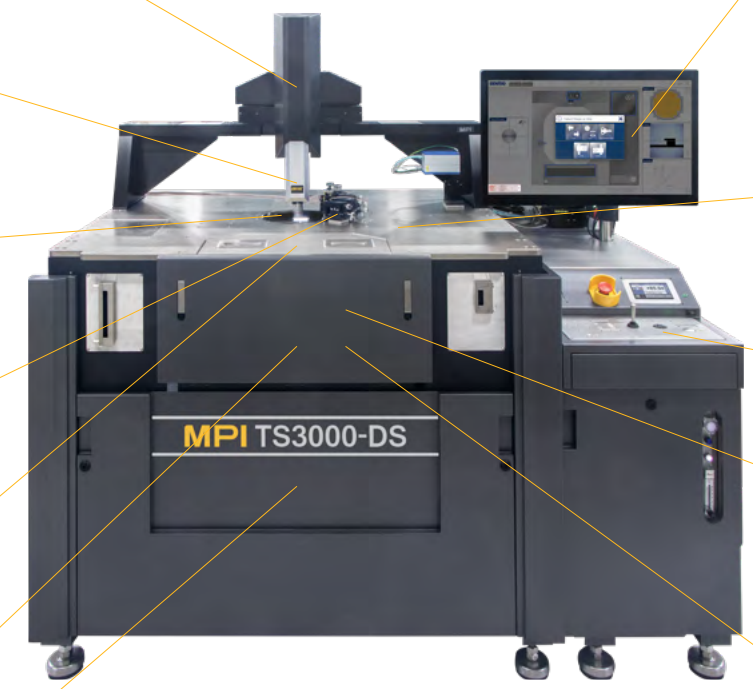
- Stable and rigid design
- Rectangular adjustments for RF positioners
- Integrated air-cooling for maximum thermal stability

Bottom Probe Platen

- For Hexapod+NanoPositioner combination
- Integrated z-travel for contact-separation movement

Integrated Vibration Isolation Table

- Incorporates a high performance vibration isolation platform
- Optimal working height for ergonomic daily operation



Software Suite SENTIO® (Windows 11)

- Simple and intuitive operation by multi-touch control, keeps training time to a minimum
- Navigation commands comparable with mobile devices, for ease of operation
- Switching between the active application and the rest of the APPs is just matter of a simple finger sweep
- Integrated RF process calibration supported by QAlibria®
- GPIB, TCP/IP interface for remote control
- Fully integrated dual sided optical testing process

SiPH Calibration Areas

- Two calibration areas on the top and bottom side
- Adjustment of the fiber height and rotation angles
- Integrated temperature compensated calibration
- Provides highest level of alignment accuracy

Integrated Hardware Control Panel

- For fast, safe and direct system control
- Obstruction-free positioning of the keyboard and mouse

GridChuck™

- For 300 mm wafer, wafer shards and singulated dies
- Designed for electrical probing on top and/or optical from the bottom
- Customized backside opening, compatible w/ the wafer layout
- Insulated banana chuck connection

Thermal Chuck Integration

- Thermal GridChuck control via touch screen
- Convenient front-end operator access
- Temperature capability from room temperature to 150°C

**COUPE™ is a trademark of Taiwan Semiconductor Manufacturing Company (TSMC).*